

AMENDMENTS TO THE CLAIMS

This Listing of Claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Currently Amended) A wiring substrate manufacturing method comprising a step of forming a wiring of a wiring substrate, which forming step includes a projection by an exposure treatment in which exposure light from a photomask is transmitted through a projection lens to pattern a photoresist, the using a photomask having which has a shade pattern formed on a plate, said shade pattern containing at least nano particles and a binder.

2. (Previously Presented) The wiring substrate manufacturing method according to claim 1, wherein said nano particles comprise a black pigment, and the wiring substrate manufacturing method further comprises a step of forming each of said shade patterns on said plate by printing a shade material containing said black pigment of 30% or less.

3. (Currently Amended) The wiring substrate manufacturing method according to claim 1, wherein said shade pattern ~~correspond~~ corresponds to said wirings, respectively.

4. (Currently Amended) The wiring substrate manufacturing method according to claim 1, wherein an area of said shade pattern is ~~relatively~~ smaller than an area of a light transmission region having no shade pattern.

5. (Currently Amended) The wiring substrate manufacturing method according to claim 1, further comprising the steps of:

forming a line pattern for forming said wiring, in a thickness direction of a wiring substrate main body; and

forming a hole pattern which is a pattern for forming said wirings and which connects, to one another, line patterns located on ~~differencee~~ different wiring layers.

6. (Original) The wiring substrate manufacturing method according to claim 1, wherein said nano particles consist of carbon.

7. (Original) The wiring substrate manufacturing method according to claim 1, further comprising a step of mounting one or a plurality of electronic components on a first surface of said substrate.

8. (Original) The wiring substrate manufacturing method according to claim 7, further comprising a step of mounting, while a second surface opposite to the first surface of said substrate faces a printed wiring substrate,

the substrate on which said one or plurality of electronic components are mounted, on a printed wiring substrate.

9-17. (Cancelled).

18. (Previously Presented) The wiring substrate manufacturing method according to Claim 1, wherein the plate having said shade pattern formed thereon is a glass plate.

19. (Previously Presented) The wiring substrate manufacturing method according to Claim 1, wherein the nanoparticles scatter light used by the exposure treatment.

20. (New) The wiring substrate manufacturing method according to Claim 19, wherein the nanoparticles are 200nm or less in particle diameter.

21. (New) The wiring substrate manufacturing method according to Claim 20, wherein the binder comprises a resist material containing light absorber that absorbs exposure light.

22. (New) The wiring substrate manufacturing method according to Claim 1, wherein the binder comprises a resist material containing light absorber that absorbs exposure light.